



### **SMD Mount Receptacle**

Part No: RECE.20369.001E.01

#### **Description:**

SMD W.FL Compatible Receptacle Compatible with I-PEX MHFIII, Hirose W.FL, Hirose W.FL2

### Features:

Mating Height: 1.6mm Max 5000pcs per reel Dimensions: 2 x 2 x 0.85mm Diameter: 1.4mm RoHS & Reach Compliant



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Changelog

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### 1. Introduction



Part of the Taoglas SMD Mount Receptacle the RECE.20369.001E.01 is a 3-pad type wire-to-board SMD Receptacle solution that is ultra-small, lightweight and low profile (1.6mm MAX.) with an operational frequency range of DC to 6 GHz. Taoglas the RECE.20369.001E.01 is gold plated to have superior performance and allow easy mounting of the male RF connector.

Packaged on tape and reel, this receptacle is designed to be placed with automatic "pick and place" equipment for ease of installation.

The RECE.20369.001E.01 acts as a 50 Ohm transmission line to connect the micro-miniature RF connector to the printed circuit board. It is fully compatible with I-PEX MHFIII, Hirose W.FL and all other available W.FL compatible connectors .

#### Applicable Technologies:

The RECE.20369.001E.01 receptacles are commonly integrated into GSM module, GPS module, Wireless LAN modules.

For further information, please contact your regional Taoglas customer support team.



# 2. Specifications

	Electrical
Operation Frequency	DC to 6 GHz
VSWR	1.3 Max at DC~3 GHz
VSWK	1.4 Max at 3~6 GHz
Nominal Impedance	50 Ohm
Rated Voltage	60V AC
Rated Current	1A Max.
Contact Resistance	Subject mated contacts assembled in housing to 20mV Max. open circuit at 10mA Max
Withstand Voltage	AC 200V/minute
Insulation Resistance	Impressed voltage 100V DC for 1min Initial : 500M $\Omega$ Min. Final : 100M $\Omega$ Min.
Dielectric Withstanding Voltage	200V AC for 1 minute
Current leakage	0.5mA Max
Temperature	-40 to +90°C

	Material
Outer Contact	Copper Alloy (Au plating)
Centre Contact	Copper Alloy (Au plating)
Insulator	LCP UL94-V0

	Environmental
Durability	per EIA-364-09C (2-3 cycles per min @ 30 cycles)
Vibration	10Hz -> 100Hz -> 10Hz for 20 mins.
Peak value of acceleration	1.5mm or 59m/s2 (6G)
Direction	3 axis 5 Cycles
	Mechanical Shock
Accelerate Velocity	735m/s2 (75G)
Waveform	Half-sine shock plus.
Duration	11m sec.
Direct Current	1mA
Direction	In $\pm X$ , $\pm Y$ and $\pm Z$ axes.
Cycle	3 cycles for each direction, totally 18 cycles

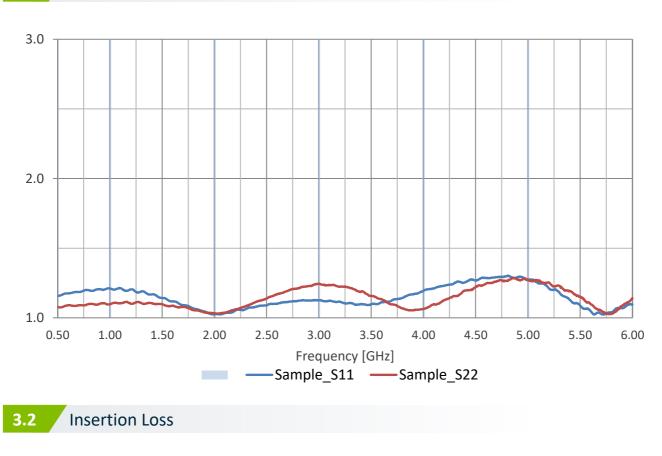


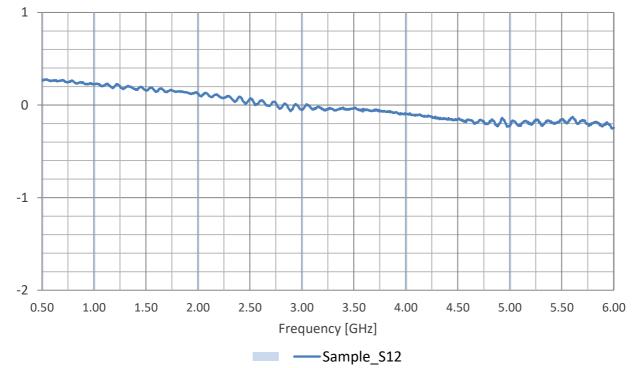
Thermal Shock (40°C for 30min	is to 5~35°C for 5 minutes to 90°C for 30mins to 5~35°C for 5 minutes)
Transition Time	5 minutes
Cycles	5
Humidity	90~95% RH
Temperature	40+/- 2°C
Duration	96 hours
	Salt Water Spray
Temperature	35+/- 2°C
Salt Water Density	5+/-1% (by weight)
Duration	48 Hours
High temperature life	90+/- 2°C for 96 hours
Cold temperature life	-40+/- 2°C for 96 hours
	H2S gas
Temperature	40+/-2°C
Relative Humidity	80 +/-5% RH
Gas H2S	3+/-1 ppm
Duration	96 Hours
Moisture Sensitivity Level	3



### 3. Connector Data

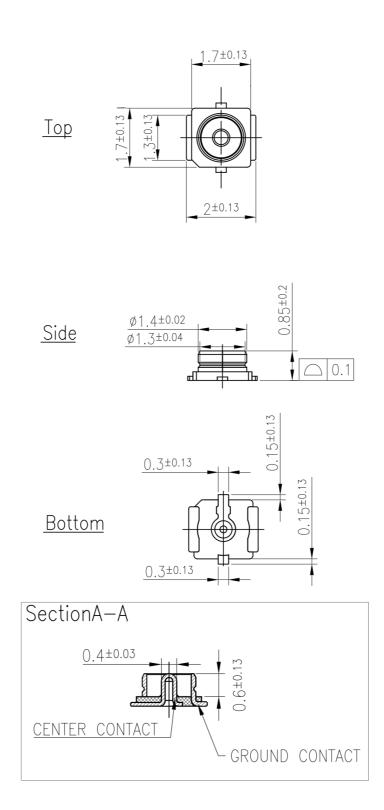








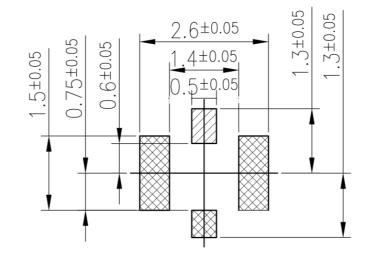
## Mechanical Drawing (Units: mm)



4.



## Footprint



Notes:

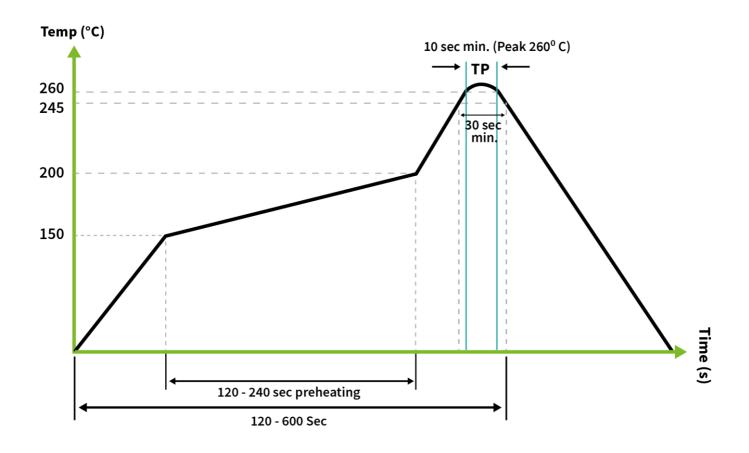


5.



6.

The RECE.20369.001E.01 can be assembled by following the recommended soldering temperatures are as follows:



\*Temperatures listed within a tolerance of +/- 10º C

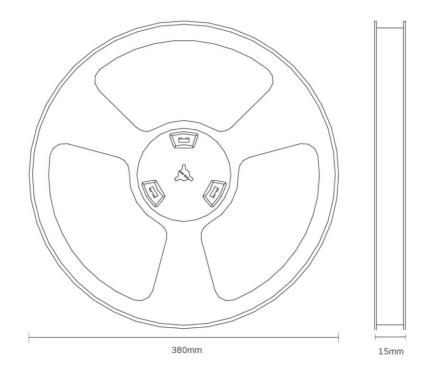
Smaller components are typically mounted on the first pass, however, we do advise mounting the RECE.20369.001E.01 when placing larger components on the board during subsequent reflows.

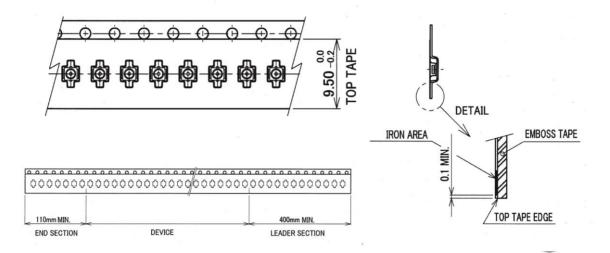


## Packaging

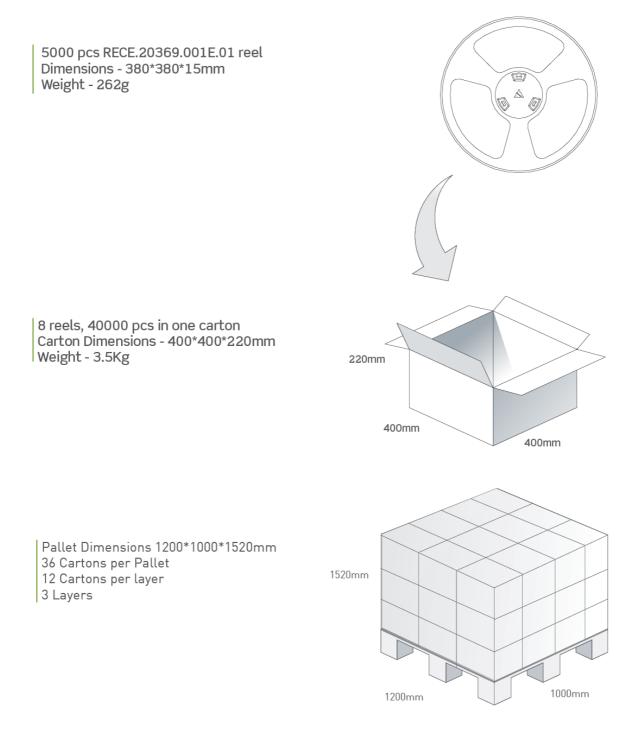
7.

5000 pcs RECE.20369.001E.01 reel Dimensions - 380\*380\*15mm Weight -262g











Changelog for the datasheet

SPE-16-8-033 - RECI	E.20369.001E.01
Revision: F (Current	Version)
Date:	2023-09-07
Changes:	Updated Solder Reflow Information
Changes Made by:	Cesar Sousa

#### **Previous Revisions**

Revision: E	
Date:	2023-03-03
Changes:	Updated description
Changes Made by:	Cesar Sousa

Revision: D	
Date:	2022-01-27
Changes:	Updated Solder Reflow Diagram & Adding MSL.
Changes Made by:	Gary West

Revision: C	
Date:	2021-07-15
Changes:	Updated Solder Reflow Diagram & Adding MSL.
Changes Made by:	Gary West

Revision: B	
Date:	2021-02-03
Changes:	Following EC-20-8-036
Changes Made by:	Jack Conroy

Date:  2016-04-21    Notes:
Author: Jack Conroy